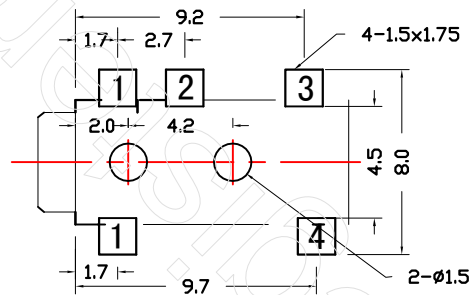
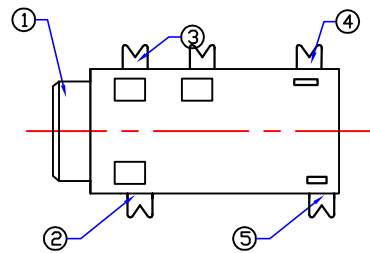
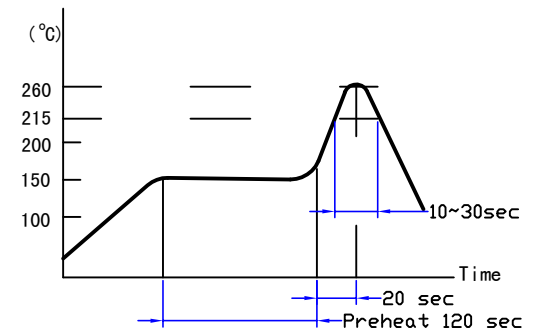


SCHMATIC



P. C. B TERMINAL POSITION



REFLOW SOLDERING CONDITIONS

No	Parts	Material	Qty	Finish	Specifications	PJ-207A-SMD
1	Body	PA66+30%Fider	1	94V-0	Rating: DC 12V 1A	TITLE: PHONE JACK
2	Chip Terminal	t:0.20 Cu-Tl Alloy	1	Ep-Cu/Ni 1, Ag 1(Silver Plating)	Contact Resistance: 30m ohm max	UNLESS OTHERWISE SPECIFIED TOLERANCE ±0.1 ANGLE TOL ±30"
3	Sleeve Terminal	t:0.20 Cu-Tl Alloy	1	Ep-Cu/Ni 1, Ag 1(Silver Plating)	Insulation Resistance: 100M ohm at 500V DC	
4	Ring Terminal	t:0.20 Cu-Tl Alloy	1	Ep-Cu/Ni 1, Ag 1(Silver Plating)	Dielectric Strength: AC 500V for 1 Minute	
5	Ring Terminal	t:0.20 Cu-Tl Alloy	1	Ep-Cu/Ni 1, Ag 1(Silver Plating)	Insertion & Extraction Force: 0.3-2.0kgf	
					Life: 5.000 Cycles	
					Taping: 1.000 Pcs/Reel	DRAWN: jja
						DATE: 2004-06-18
						CHECKED:
						DATE:
						APPROVED:
						DATE:

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